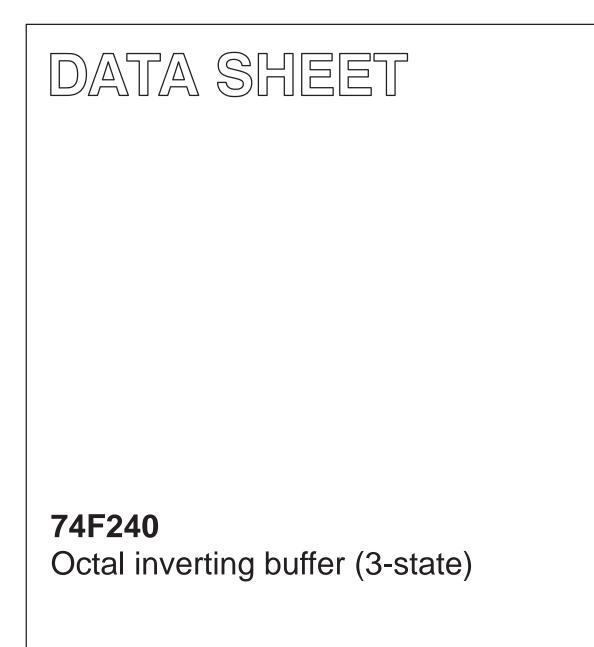
# INTEGRATED CIRCUITS



Product data Supersedes data of 2002 Mar 18 2004 Feb 25



Philips Semiconductors

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### **FEATURES**

- Octal bus interface
- 3-state buffer outputs sink 64 mA
- 15 mA source current

### DESCRIPTION

The 74F240 is an octal inverting buffer that is ideal for driving bus lines of buffer memory address registers. The outputs are all capable of sinking 64 mA and sourcing up to 15 mA. The device features two output enables, each controlling four of the 3-state outputs.

Т	YPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
7	'4F240	4.3 ns	37 mA

### **ORDERING INFORMATION**

	ORDER CODE	
DESCRIPTION	COMMERCIAL RANGE V <sub>CC</sub> = 5 V $\pm$ 10%, T <sub>amb</sub> = 0 °C to +70 °C	PKG DWG #
20-pin plastic DIP	N74F240N	SOT146-1
20-pin plastic SOL	N74F240D	SOT163-1
20-pin plastic SSOP II	N74F240DB	SOT339-1

## INPUT AND OUTPUT LOADING AND FAN OUT TABLE

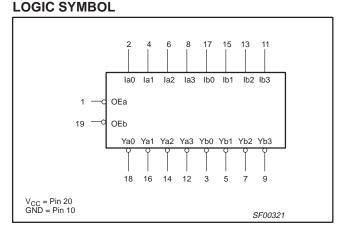
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
lan, Ibn	Data inputs	1.0/1.67	20 µA/1.0 mA
OEa, OEb	Output enable inputs (Active-LOW)	1.0/0.33	20 μA/0.2 mA
Yan, Ybn	Data outputs	750/106.7	15 mA/64 mA

Note to input and output loading and fan out table

One (1.0) FAST unit load is defined as: 20 µA in the HIGH state and 0.6 mA in the LOW state.

## **PIN CONFIGURATION**

OEa 1 20 V <sub>CC</sub> la0 2 19 OEb Vb0 3 18 Va0
Ia1     4     17     Ib0       Yb1     5     16     Ya1       Ia2     6     15     Ib1       Yb2     7     14     Ya2       Ia3     8     13     Ib2       Yb3     9     12     Ya3       GND     10     11     Ib3
GND 10 11 lb3 SF00320

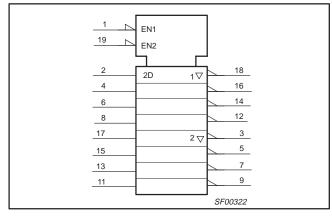


## 74F240

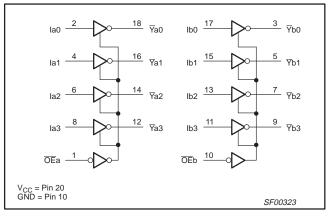
#### Product data

## 74F240

### **IEC/IEEE SYMBOL**



### LOGIC DIAGRAM



## **FUNCTION TABLE**

	INP	OUT	PUTS		
OEa	la	OEb	lb	Ya	Yb
L	L	L	L	Н	Н
L	Н	L	Н	L	L
Н	Х	Н	Х	Z	Z

NOTES:

H = High voltage level

L = Low voltage level

X = Don't care

Z = High impedance "off" state

## **ABSOLUTE MAXIMUM RATINGS**

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V <sub>CC</sub>	Supply voltage	-0.5 to +7.0	V
V <sub>IN</sub>	Input voltage	-0.5 to +7.0	V
I <sub>IN</sub>	Input current	-30 to +5	mA
V <sub>OUT</sub>	Voltage applied to output in high output state	–0.5 to $V_{CC}$	V
I <sub>OUT</sub>	Current applied to output in low output state	128	mA
T <sub>amb</sub>	Operating free air temperature range	0 to +70	°C
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C

### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL			UNIT		
STWBUL	PARAMETER	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5.0	5.5	V
V <sub>IH</sub>	High-level input voltage	2.0			V
V <sub>IL</sub>	Low-level input voltage			0.8	V
I <sub>lk</sub>	Input clamp current			-18	mA
I <sub>OH</sub>	High-level output current			-15	mA
I <sub>OL</sub>	Low-level output current			64	mA
T <sub>amb</sub>	Operating free air temperature range	0		+70	°C

#### Product data

### DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER		TE	ST CONDITIONS	1	LIMITS			UNIT
						MIN	TYP <sup>2</sup>	MAX	1
				1 2 m 4	±10%V <sub>CC</sub>	2.4			V
V	High-level output voltage		$V_{CC} = MIN; V_{IL}$	I <sub>OH</sub> = -3 mA	$\pm 5\% V_{CC}$	2.7	3.4		V
V <sub>OH</sub>	High-level output voltage		= MAX; V <sub>IH</sub> = MIN	I <sub>OH</sub> = –15 mA	±10%V <sub>CC</sub>	2.0			V
			$I_{OH} = -15 IIIA$	±5%V <sub>CC</sub>	2.0			V	
M			$V_{CC} = MIN; V_{IL}$		±10%V <sub>CC</sub>			0.50	V
V <sub>OL</sub>	Low-level output voltage	vel output voltage $=$ MAX; V <sub>IH</sub> = $I_{OL} =$ MAX MIN		$I_{OL} = MAX$	±5%V <sub>CC</sub>		0.42	0.50	V
V <sub>IK</sub>	Input clamp voltage	$V_{CC} = MIN; I_I = I_{IK}$				-0.73	-1.2	V	
l <sub>l</sub>	Input current at maximum input	$V_{CC} = MAX; V_I = 7.0 V$					100	μA	
I <sub>IH</sub>	High-level input current		$V_{CC} = MAX; V_I = 2.7 V$					20	μΑ
IIL	Low-level input current		$V_{CC} = MAX; V_I = 0.5 V$					-1.0	mA
I <sub>OZH</sub>	Off-state output current, high-level voltage applied		$V_{CC} = MAX, V_O =$	= 2.7 V				50	μA
I <sub>OZL</sub>	Off-state output current, low-level voltage applied		V <sub>CC</sub> = MAX, V <sub>O</sub> = 0.5 V					-50	μA
I <sub>OS</sub>	Short-circuit output current <sup>3</sup>		V <sub>CC</sub> = MAX			-100		-225	mA
		I <sub>CCH</sub>					12	18	mA
I <sub>CC</sub>	Supply current (total)	I <sub>CCL</sub>	V <sub>CC</sub> = MAX				50	70	mA
		I <sub>CCZ</sub>	]				35	45	mA

#### NOTES:

 For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
 All typical values are at V<sub>CC</sub> = 5 V, T<sub>amb</sub> = 25 °C.
 Not more than one output should be shorted at a time. For testing I<sub>OS</sub>, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

## 74F240

### **AC ELECTRICAL CHARACTERISTICS**

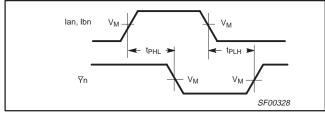
					LIN	IITS		
SYMBOL	PARAMETER	TEST CONDITION	T <sub>amb</sub> = +25 °C V <sub>CC</sub> = +5.0 V C <sub>L</sub> = 50 pF; R <sub>L</sub> = 500 Ω			T <sub>amb</sub> = 0 °C V <sub>CC</sub> = +5.0 C <sub>L</sub> = 50 pF;	UNIT	
			MIN	ТҮР	MAX	MIN	MAX	1
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay Ian, Ibn to Yn	Waveform 1	3.0 2.0	4.5 3.0	6.5 4.5	3.0 2.0	7.5 5.0	ns
t <sub>PZH</sub> t <sub>PZL</sub>	Output enable time to high or low level	Waveform 2 & 3	3.0 4.5	5.0 6.5	7.5 8.5	3.0 4.0	9.0 10.0	ns
t <sub>PHZ</sub> t <sub>PLZ</sub>	Output disable time from high or low level	Waveform 2 & 3	3.0 3.0	5.5 5.0	7.0 7.0	3.0 3.0	7.5 7.5	ns

NOTES:

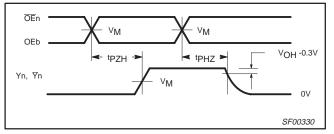
1.  $|t_{PN} actual - t_{PM} actual|$  for any output compared to any other output where N and M are either LH or HL.

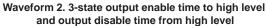
## 74F240

### AC WAVEFORMS

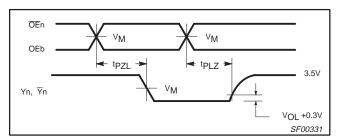


Waveform 1. Propagation delay for inverting outputs





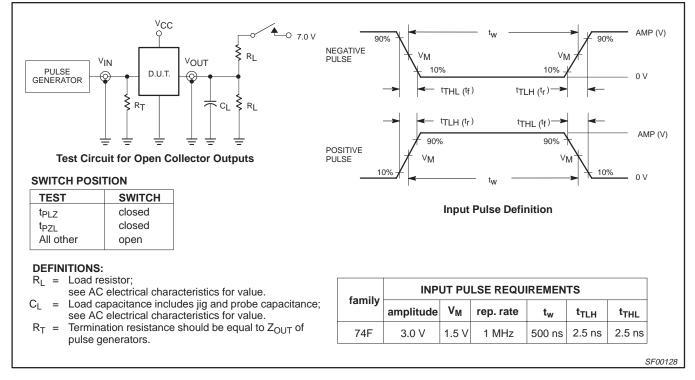
## **TEST CIRCUIT AND WAVEFORMS**



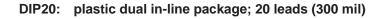
Waveform 3. 3-state output enable time to low level and output disable time from low level

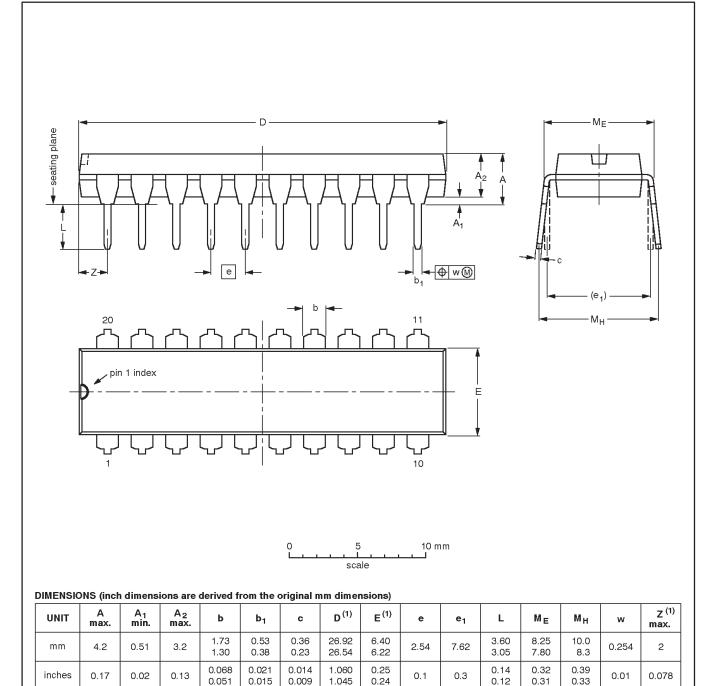
Notes to AC waveforms

1. For all waveforms,  $V_{M}$  = 1.5 V.









#### Note

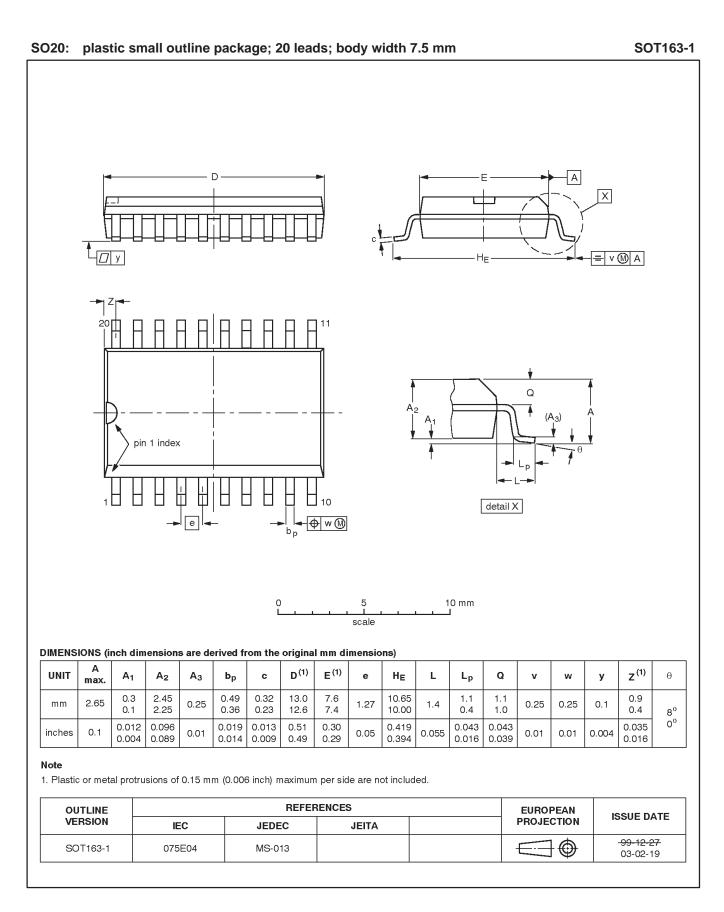
1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE		REFERENCES EURO		EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION	1350E DATE
SOT146-1		MS-001	SC-603			<del>99-12-27</del> 03-02-13

74F240

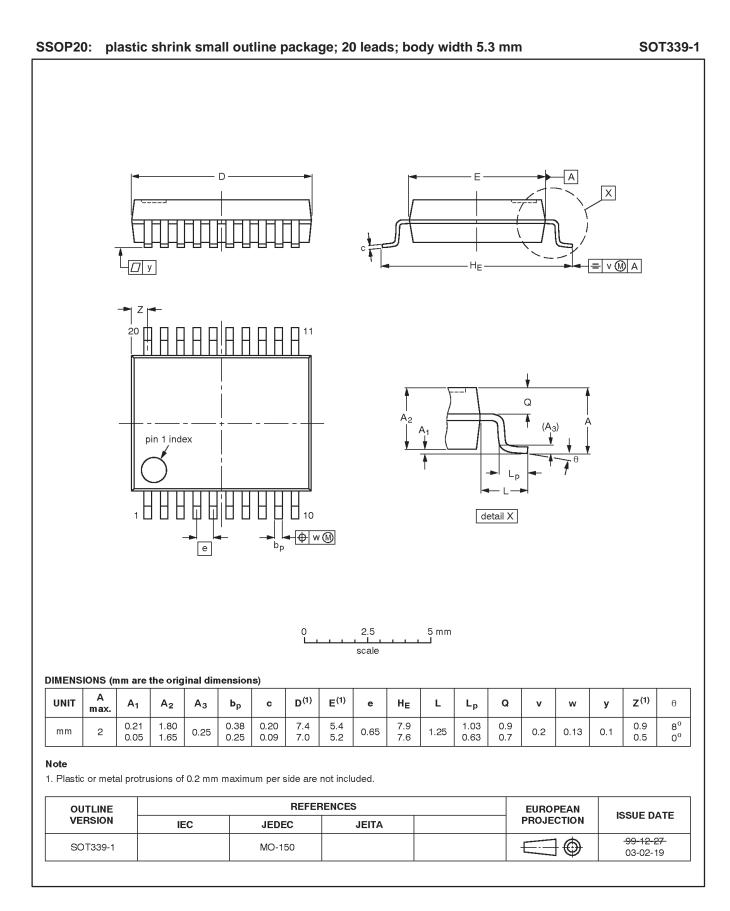
SOT146-1

## 74F240



Product data

## 74F240



74F240

## **REVISION HISTORY**

Rev	Date	Description
_4	20040225	Product data (9397 750 12941); supersedes data sheet 74F240_241_241A_3 of 2002 Mar 18 (9397 750 09571).
		Modifications:
		<ul> <li>Delete all references to 74F241A (product discontinued).</li> </ul>
		<ul> <li>Separate 74F240 and 74F241 into standalone data sheets.</li> </ul>
_3	20020318	Product data (9397 750 09571); supersedes previous version.

#### Data sheet status

Level	Data sheet status <sup>[1]</sup>	Product status <sup>[2] [3]</sup>	Definitions
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

#### Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Date of release: 02-04

Document order number:

9397 750 12941

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